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SUITE CLASSIFICATION

PATENT NUMBER

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U.S. UTILITY Patent Application

QUIP

PATENT DATE

SCANNED BY SPIDER

APPLICATION NO. 09/945241	CONT/PRIOR F	CLASS <u>257</u> <u>438</u>	SUBCLASS <u>612</u>	ART UNIT <u>2015</u> <u>2812</u>	EXAMINER <u>Nguyen, H/C</u>
APPLICANTS Fumiaki Matsushima Tsutomu Ota Akira Makabe					
TITLE Method for forming a bump, semiconductor device and method of fabricating same, semiconductor chip, circuit board, and electronic instrument					
PTO-2040 12/99					

ISSUING CLASSIFICATION

Continued on Issue Six Inside Front-Jacket

TERMINAL DISCLAIMER		DRAWINGS		CLAIMS ALLOWED	
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